

Title (en)

METHOD FOR THE STRUCTURED METAL-COATING OF POLYMERIC AND CERAMIC SUPPORT MATERIALS, AND COMPOUND THAT CAN BE ACTIVATED AND IS USED IN SAID METHOD

Title (de)

VERFAHREN ZUR STRUKTURIERTEN METALLISIERUNG VON POLYMEREN UND KERAMISCHEN TRÄGERMATERIALIEN UND AKTIVIERBARE VERBINDUNG ZUR VERWENDUNG IN DIESEM VERFAHREN

Title (fr)

PROCEDE DE METALLISATION STRUCTUREE DE MATERIAUX-SUPPORTS POLYMERES ET CERAMIQUES, ET COMPOSE ACTIVABLE DESTINE A ETRE UTILISE AU COURS DE CE PROCEDE

Publication

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Application

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Abstract (en)

[origin: WO2004110118A1] The invention relates to a method for producing highly adhesive conductive structures on non-conductive supports, especially for use in electric circuits, and a surface activating compound which is used in said method. The inventive method comprises the following steps: a surface activating compound is applied and is selectively irradiated; and the irradiated areas are then metal-coated in a currentless manner so as to form metallic structures.

IPC 1-7

H05K 3/18; C23C 18/16

IPC 8 full level

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Citation (search report)

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